

# 1SMB5.0AT3G Series, SZ1SMB5.0AT3G Series

## 600 Watt Peak Power Zener Transient Voltage Suppressors

### Unidirectional

The SMB series is designed to protect voltage sensitive components from high voltage, high energy transients. They have excellent clamping capability, high surge capability, low zener impedance and fast response time. The SMB series is supplied in ON Semiconductor's exclusive, cost-effective, highly reliable SURMETIC® package and is ideally suited for use in communication systems, automotive, numerical controls, process controls, medical equipment, business machines, power supplies and many other industrial/consumer applications.

#### Features

- Working Peak Reverse Voltage Range – 5.0 V to 170 V
- Standard Zener Breakdown Voltage Range – 6.7 V to 199 V
- Peak Power – 600 W @ 1.0 ms
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- Maximum Clamp Voltage @ Peak Pulse Current
- Low Leakage < 5.0  $\mu$ A Above 10 V
- UL 497B for Isolated Loop Circuit Protection
- Response Time is Typically < 1.0 ns
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Pb-Free Packages are Available\*

#### Mechanical Characteristics

**CASE:** Void-free, transfer-molded, thermosetting plastic

**FINISH:** All external surfaces are corrosion resistant and leads are readily solderable

**MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:**  
260°C for 10 Seconds

**LEADS:** Modified L-Bend providing more contact area to bond pads

**POLARITY:** Cathode indicated by polarity band

**MOUNTING POSITION:** Any



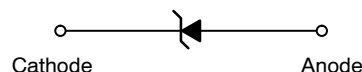
ON Semiconductor®

<http://onsemi.com>

**PLASTIC SURFACE MOUNT  
ZENER OVERVOLTAGE  
TRANSIENT SUPPRESSORS  
5.0 V – 170 V,  
600 W PEAK POWER**



SMB  
CASE 403A  
PLASTIC



#### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
xx = Device Code (Refer to page 3)  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

| Device        | Package          | Shipping†              |
|---------------|------------------|------------------------|
| 1SMBxxxAT3G   | SMB<br>(Pb-Free) | 2,500 /<br>Tape & Reel |
| SZ1SMBxxxAT3G | SMB<br>(Pb-Free) | 2,500 /<br>Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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## MAXIMUM RATINGS

| Rating                                                                                                                | Symbol          | Value       | Unit                      |
|-----------------------------------------------------------------------------------------------------------------------|-----------------|-------------|---------------------------|
| Peak Power Dissipation (Note 1) @ $T_L = 25^\circ\text{C}$ , Pulse Width = 1 ms                                       | $P_{PK}$        | 600         | W                         |
| DC Power Dissipation @ $T_L = 75^\circ\text{C}$ Measured Zero Lead Length (Note 2)<br>Derate Above $75^\circ\text{C}$ | $P_D$           | 3.0<br>40   | W<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance from Junction-to-Lead                                                                              | $R_{\theta JL}$ | 25          | $^\circ\text{C/W}$        |
| DC Power Dissipation (Note 3) @ $T_A = 25^\circ\text{C}$<br>Derate Above $25^\circ\text{C}$                           | $P_D$           | 0.55<br>4.4 | W<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance from Junction-to-Ambient                                                                           | $R_{\theta JA}$ | 226         | $^\circ\text{C/W}$        |
| Forward Surge Current (Note 4) @ $T_A = 25^\circ\text{C}$                                                             | $I_{FSM}$       | 100         | A                         |
| Operating and Storage Temperature Range                                                                               | $T_J, T_{stg}$  | -65 to +150 | $^\circ\text{C}$          |

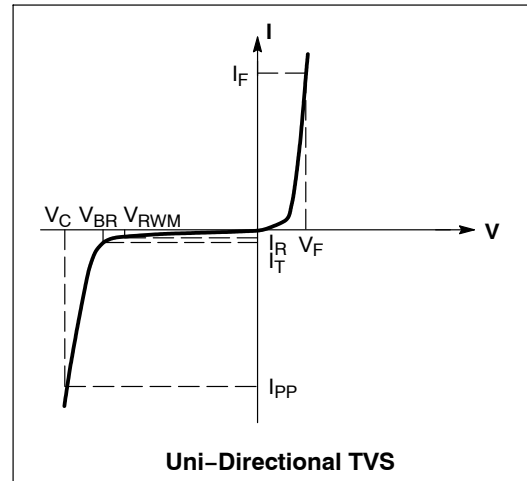
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. 10 X 1000  $\mu\text{s}$ , non-repetitive.
2. 1 in square copper pad, FR-4 board.
3. FR-4 board, using ON Semiconductor minimum recommended footprint, as shown in 403A case outline dimensions spec.
4. 1/2 sine wave (or equivalent square wave), PW = 8.3 ms, duty cycle = 4 pulses per minute maximum.

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted,  $V_F = 3.5\text{ V Max.}$  @  $I_F$  (Note 5) = 30 A)

| Symbol    | Parameter                                   |
|-----------|---------------------------------------------|
| $I_{PP}$  | Maximum Reverse Peak Pulse Current          |
| $V_C$     | Clamping Voltage @ $I_{PP}$                 |
| $V_{RWM}$ | Working Peak Reverse Voltage                |
| $I_R$     | Maximum Reverse Leakage Current @ $V_{RWM}$ |
| $V_{BR}$  | Breakdown Voltage @ $I_T$                   |
| $I_T$     | Test Current                                |
| $I_F$     | Forward Current                             |
| $V_F$     | Forward Voltage @ $I_F$                     |

5. 1/2 sine wave (or equivalent square wave), PW = 8.3 ms, non-repetitive duty cycle.





# 1SMB5.0AT3G Series, SZ1SMB5.0AT3G Series

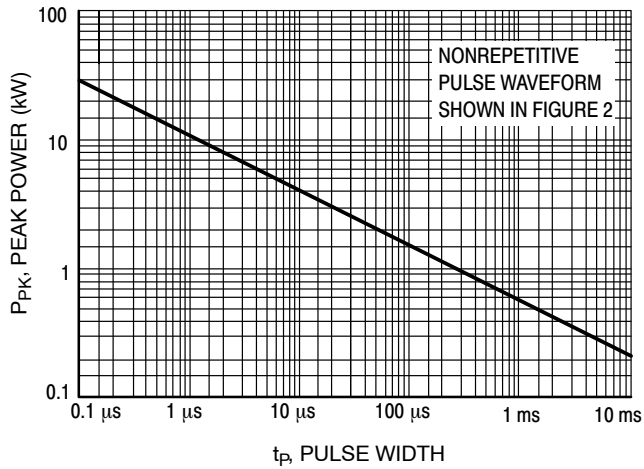


Figure 1. Pulse Rating Curve

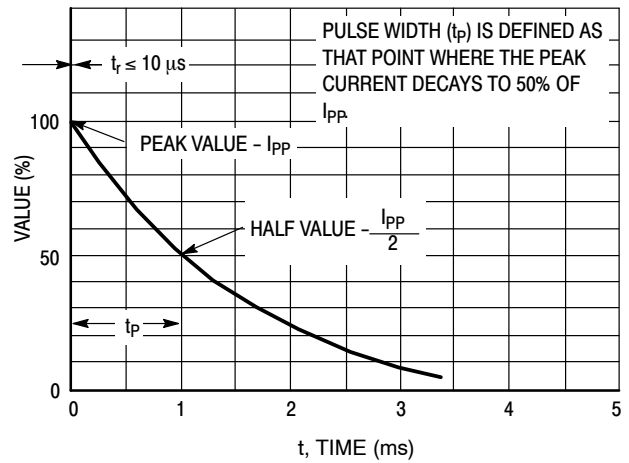


Figure 2. Pulse Waveform

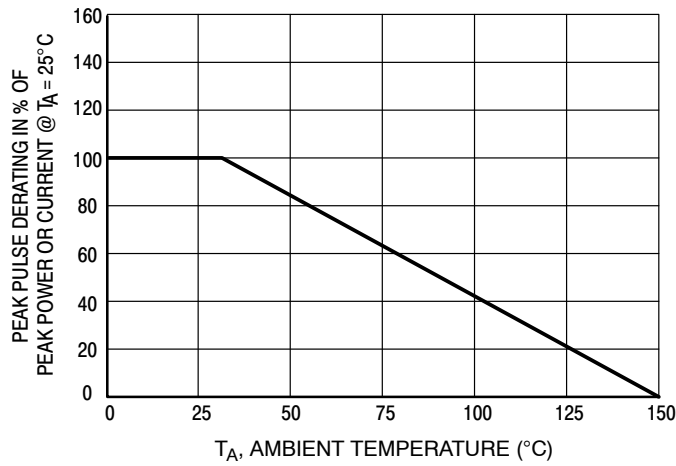


Figure 3. Pulse Derating Curve

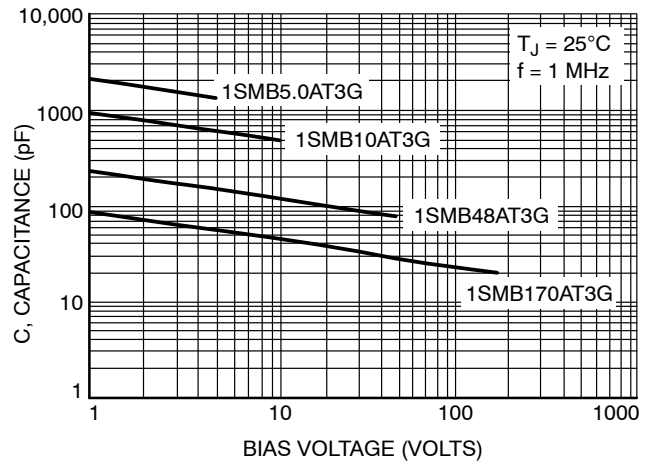


Figure 4. Typical Junction Capacitance vs. Bias Voltage

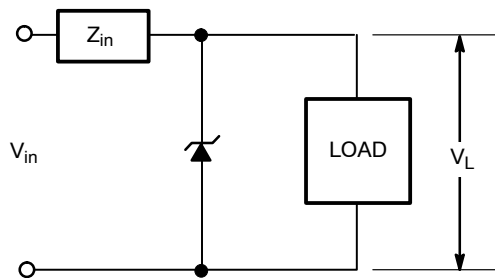


Figure 5. Typical Protection Circuit

## APPLICATION NOTES

### Response Time

In most applications, the transient suppressor device is placed in parallel with the equipment or component to be protected. In this situation, there is a time delay associated with the capacitance of the device and an overshoot condition associated with the inductance of the device and the inductance of the connection method. The capacitive effect is of minor importance in the parallel protection scheme because it only produces a time delay in the transition from the operating voltage to the clamp voltage as shown in Figure 6.

The inductive effects in the device are due to actual turn-on time (time required for the device to go from zero current to full current) and lead inductance. This inductive effect produces an overshoot in the voltage across the equipment or component being protected as shown in Figure 7. Minimizing this overshoot is very important in the application, since the main purpose for adding a transient suppressor is to clamp voltage spikes. The SMB series have a very good response time, typically  $< 1.0$  ns and negligible inductance. However, external inductive effects could produce unacceptable overshoot. Proper circuit layout,

minimum lead lengths and placing the suppressor device as close as possible to the equipment or components to be protected will minimize this overshoot.

Some input impedance represented by  $Z_{in}$  is essential to prevent overstress of the protection device. This impedance should be as high as possible, without restricting the circuit operation.

### Duty Cycle Derating

The data of Figure 1 applies for non-repetitive conditions and at a lead temperature of  $25^{\circ}\text{C}$ . If the duty cycle increases, the peak power must be reduced as indicated by the curves of Figure 8. Average power must be derated as the lead or ambient temperature rises above  $25^{\circ}\text{C}$ . The average power derating curve normally given on data sheets may be normalized and used for this purpose.

At first glance the derating curves of Figure 8 appear to be in error as the 10 ms pulse has a higher derating factor than the 10  $\mu\text{s}$  pulse. However, when the derating factor for a given pulse of Figure 8 is multiplied by the peak power value of Figure 1 for the same pulse, the results follow the expected trend.

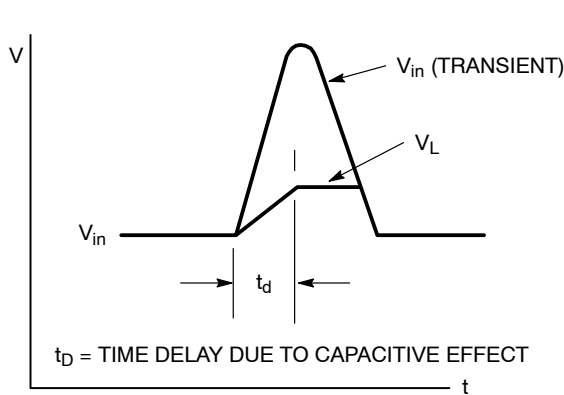


Figure 6.

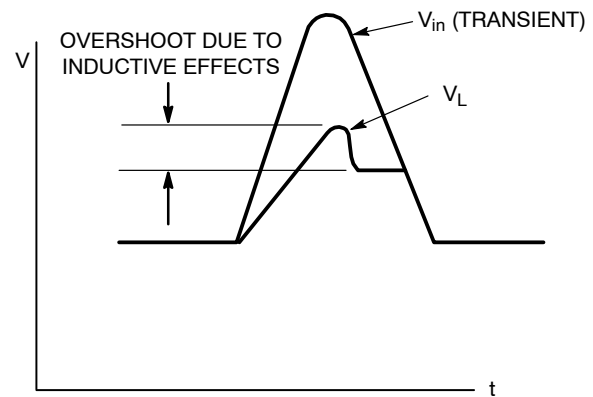


Figure 7.

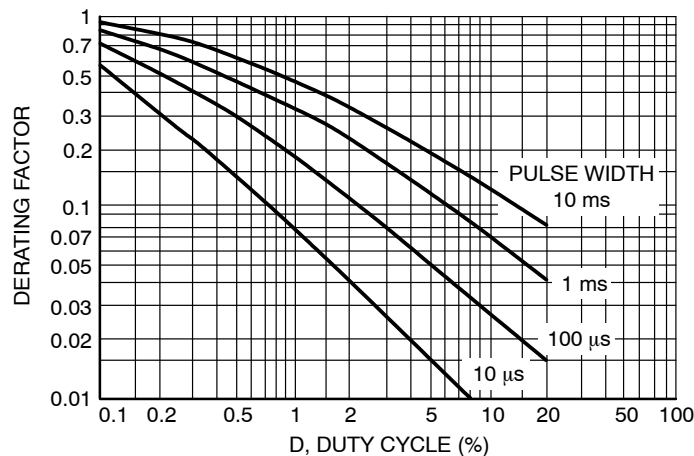


Figure 8. Typical Derating Factor for Duty Cycle

## 1SMB5.0AT3G Series, SZ1SMB5.0AT3G Series

### UL RECOGNITION

The entire series has *Underwriters Laboratory Recognition* for the classification of protectors (QVGQ2) under the UL standard for safety 497B and File #E210057. Many competitors only have one or two devices recognized or have recognition in a non-protective category. Some competitors have no recognition at all. With the UL497B recognition, our parts successfully passed several tests

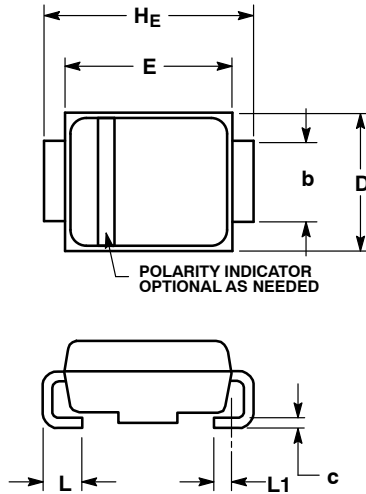
including Strike Voltage Breakdown test, Endurance Conditioning, Temperature test, Dielectric Voltage-Withstand test, Discharge test and several more.

Whereas, some competitors have only passed a flammability test for the package material, we have been recognized for much more to be included in their Protector category.

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## PACKAGE DIMENSIONS

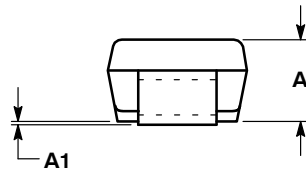
### SMB CASE 403A-03 ISSUE H



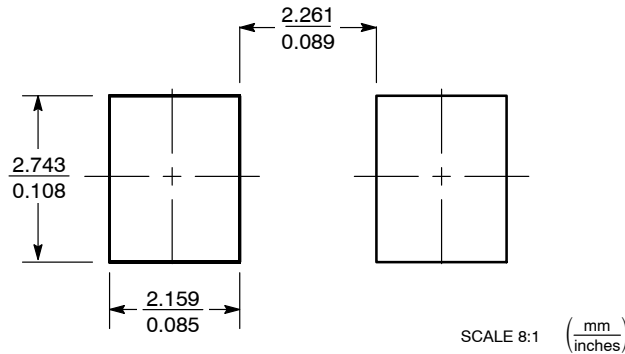
#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

| DIM | MILLIMETERS |      |      | INCHES    |       |       |
|-----|-------------|------|------|-----------|-------|-------|
|     | MIN         | NOM  | MAX  | MIN       | NOM   | MAX   |
| A   | 1.90        | 2.20 | 2.28 | 0.075     | 0.087 | 0.090 |
| A1  | 0.05        | 0.10 | 0.19 | 0.002     | 0.004 | 0.007 |
| b   | 1.96        | 2.03 | 2.20 | 0.077     | 0.080 | 0.087 |
| c   | 0.15        | 0.23 | 0.31 | 0.006     | 0.009 | 0.012 |
| D   | 3.30        | 3.56 | 3.95 | 0.130     | 0.140 | 0.156 |
| E   | 4.06        | 4.32 | 4.60 | 0.160     | 0.170 | 0.181 |
| HE  | 5.21        | 5.44 | 5.60 | 0.205     | 0.214 | 0.220 |
| L   | 0.76        | 1.02 | 1.60 | 0.030     | 0.040 | 0.063 |
| L1  | 0.51 REF    |      |      | 0.020 REF |       |       |



## SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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